

C3M0900170J

1700V 900mΩ Silicon Carbide Power MOSFET
N-Channel Enhancement Mode

Features

- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- 12V..18V / 0V V_{GS} compatible with most flyback controllers
- Ultra-low drain-gate capacitance
- Qualified to operate under high humidity and high temperature environmental conditions
- Halogen free, RoHS compliant

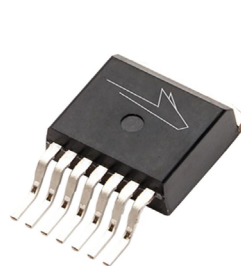
Benefits

- Smooth switching waveforms
- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Increases system switching frequency
- Increases system reliability

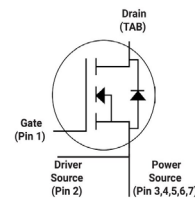
Typical Applications

- Auxillary power supplies
- Switch Mode Power Supplies
- High-Voltage capacitive loads

Package



TO-263-7



Orderable Part Number	Package	Marking
C3M0900170J-TR	TO-263-7L	C3M0900170J

Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	V_{DS}			1700	V	$T_C = 25^\circ\text{C}$	
Maximum Gate - Source Voltage (Transient)	$V_{GS(max)}$	-8		+20		Transient	
Operational Turn-On Gate-Source Voltage			+12...+18			Static	
Operational Turn-Off Gate-Source Voltage			-4...0				
DC Continuous Drain Current	I_D			4.4	A	$V_{GS} = 15\text{ V}, T_C = 25^\circ\text{C}, T_J \leq 175^\circ\text{C}$	Note 2
				3.3		$V_{GS} = 15\text{ V}, T_C = 100^\circ\text{C}, T_J \leq 175^\circ\text{C}$	
Pulsed Drain Current	I_{DM}			15		t_{pmax} limited by T_{Jmax} $V_{GS} = 15\text{ V}, T_C = 25^\circ\text{C}$	Fig. 22
Power Dissipation	P_D			41	W	$T_C = 25^\circ\text{C}, T_J = 175^\circ\text{C}$	Fig. 20
Operating Junction and Storage Temperature	T_J, T_{stg}			-55 to +175	$^\circ\text{C}$		
Solder Temperature	T_L			260			

Note (1): Review application Note PRD-04814 for additional details

Note (2): Verified by design


Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1700			V	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	3.1	4.2	V	$V_{DS} = V_{GS}, I_D = 0.55\text{ mA}$	Fig. 11
			2.6		V	$V_{DS} = V_{GS}, I_D = 0.55\text{ mA}, T_J = 175^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current		1	50	μA	$V_{DS} = 1700\text{ V}, V_{GS} = 0\text{ V}$	
I_{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		900	1250	m Ω	$V_{GS} = 15\text{ V}, I_D = 1.99\text{ A}$	Fig. 4, 5, 6
			1938			$V_{GS} = 15\text{ V}, I_D = 1.99\text{ A}, T_J = 175^\circ\text{C}$	
g_{fs}	Transconductance		1		S	$V_{DS} = 20\text{ V}, I_{DS} = 1.99\text{ A}$	Fig. 7
			1			$V_{DS} = 20\text{ V}, I_{DS} = 1.99\text{ A}, T_J = 175^\circ\text{C}$	
C_{iss}	Input Capacitance		202		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to }1200\text{ V}$ $F = 100\text{ kHz}$ $V_{AC} = 25\text{ mV}$	Fig. 17, 18
C_{oss}	Output Capacitance		8				
C_{rss}	Reverse Transfer Capacitance		1.4				
E_{oss}	C_{oss} Stored Energy		8		μJ		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		10		pF	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to }1200\text{ V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		13		pF		
E_{ON}	Turn-On Switching Energy (External Diode)		128		μJ	$V_{DS} = 1200\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}, I_D = 1.99\text{ A},$ $R_{G(ext)} = 2.5\text{ }\Omega, L = 1707\text{ }\mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE	Fig. 26, 28
E_{OFF}	Turn Off Switching Energy (External Diode)		13				
$t_{d(on)}$	Turn-On Delay Time		20		ns	$V_{DD} = 1200\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 1.99\text{ A}, R_{G(ext)} = 2.5\text{ }\Omega, T_J = 175^\circ\text{C},$ $L = 1707\text{ }\mu\text{H}$ Timing relative to V_{DS} Inductive load	Fig. 27, 28
t_r	Rise Time		16				
$t_{d(off)}$	Turn-Off Delay Time		20				
t_f	Fall Time		42				
$R_{G(int)}$	Internal Gate Resistance		31		Ω	$f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$	
Q_{gs}	Gate to Source Charge		4		nC	$V_{DS} = 1200\text{ V}, V_{GS} = -4\text{ V}/15\text{ V}$ $I_D = 1.99\text{ A}$ Per IEC60747-8-4 pg 21	Fig. 12
Q_{gd}	Gate to Drain Charge		2				
Q_g	Total Gate Charge		8				

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 1200V

$C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 1200V


Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.7		V	$V_{GS} = -4\text{ V}, I_{SD} = 1\text{ A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.2		V	$V_{GS} = -4\text{ V}, I_{SD} = 1\text{ A}, T_J = 175^\circ\text{C}$	
I_S	Continuous Diode Forward Current	5.8		A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
I_{SM}	Diode pulse Current		15	A	$V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{Jmax}	
t_{rr}	Reverse Recover time	22		ns	$V_{GS} = -4\text{ V}, I_{SD} = 1.99\text{ A}, V_R = 1200\text{ V}$ $dif/dt = 546\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	50		nC		
I_{rm}	Peak Reverse Recovery Current	5		A		
t_{rr}	Reverse Recover time	28		ns	$V_{GS} = -4\text{ V}, I_{SD} = 1.99\text{ A}, V_R = 1200\text{ V}$ $dif/dt = 246\text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	
Q_{rr}	Reverse Recovery Charge	46		nC		
I_{rm}	Peak Reverse Recovery Current	3		A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	3.0	3.6	$^\circ\text{C}/\text{W}$		Fig. 21



Typical Performance

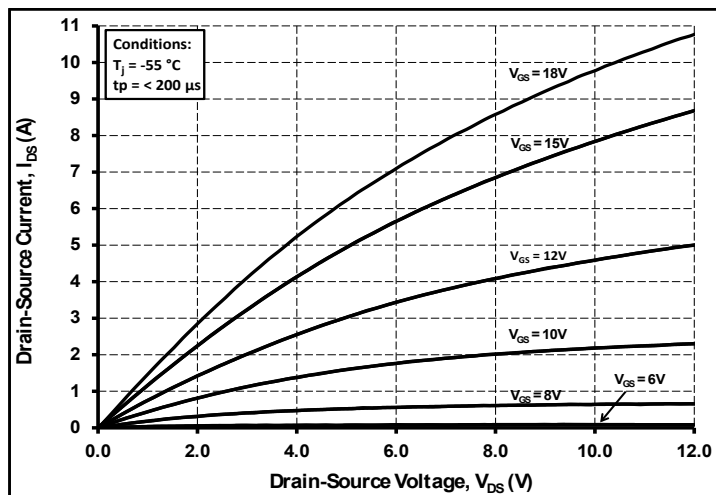
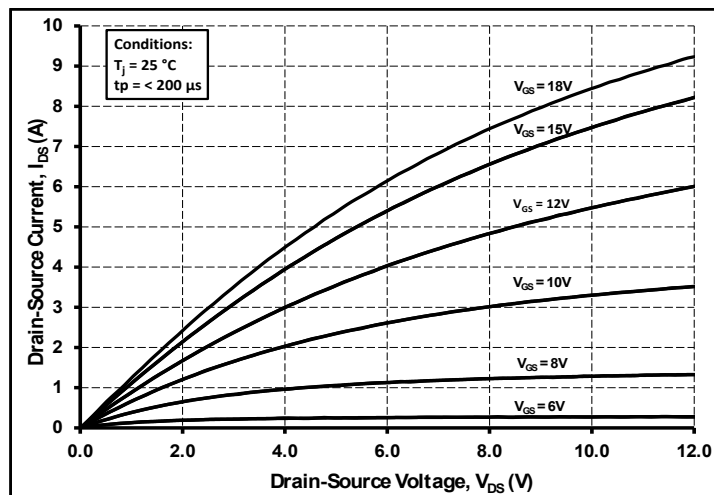
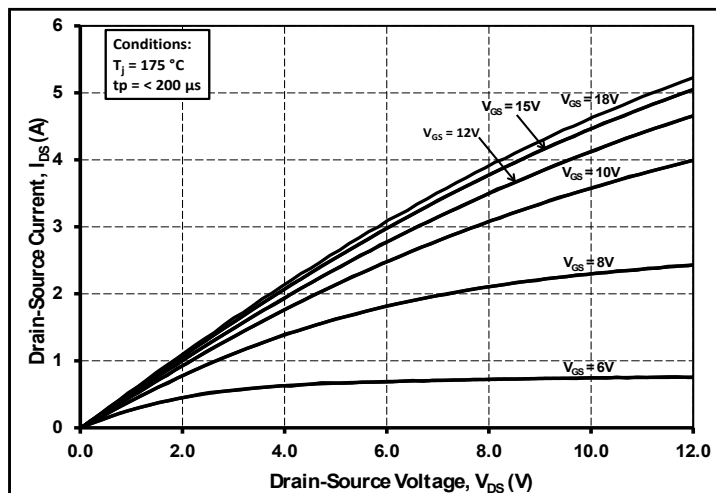
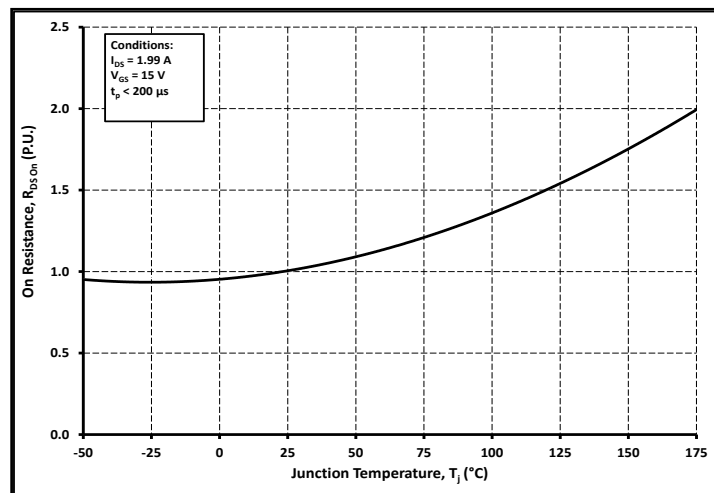
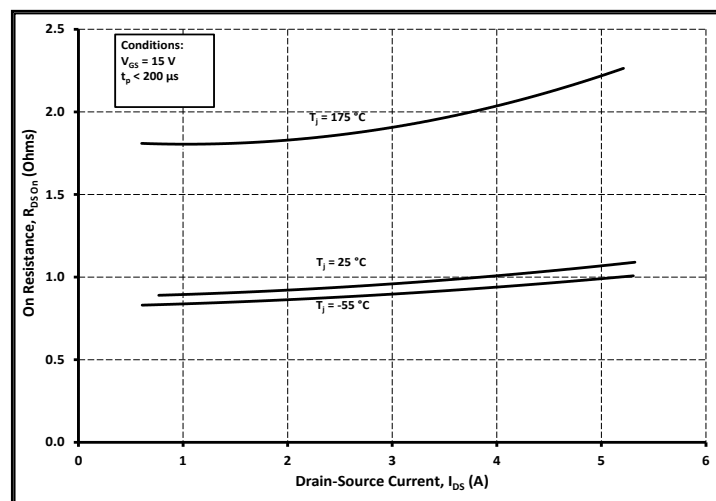
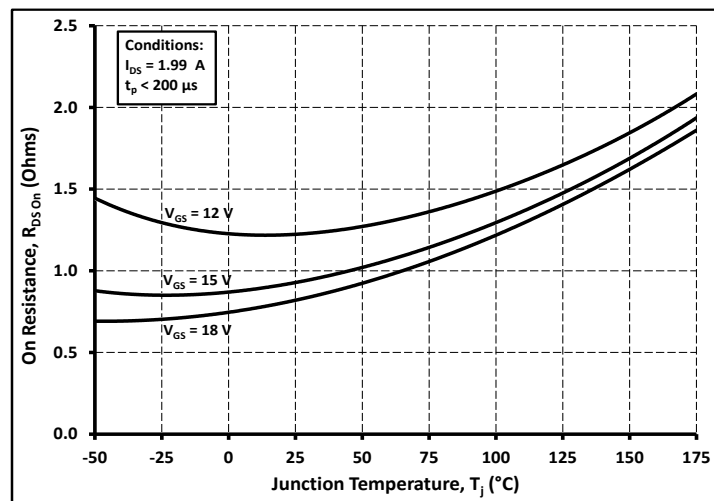
Figure 1. Output Characteristics $T_j = -55\text{ }^{\circ}\text{C}$ Figure 2. Output Characteristics $T_j = 25\text{ }^{\circ}\text{C}$ Figure 3. Output Characteristics $T_j = 175\text{ }^{\circ}\text{C}$ 

Figure 4. Normalized On-Resistance vs. Temperature

Figure 5. On-Resistance vs. Drain Current
For Various TemperaturesFigure 6. On-Resistance vs. Temperature
For Various Gate Voltage

Typical Performance

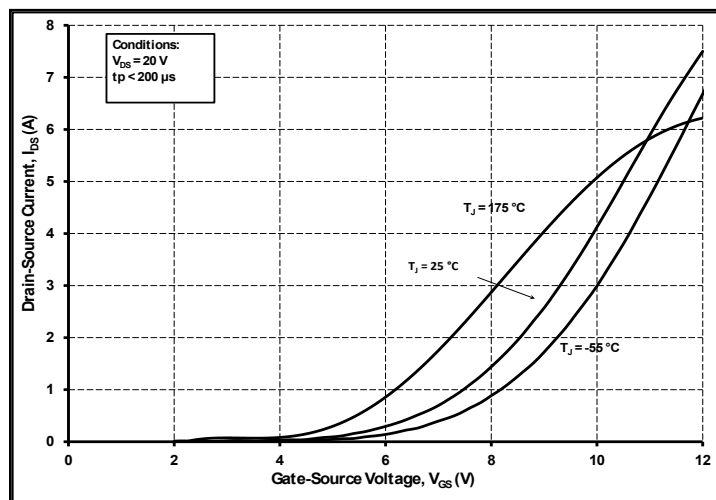


Figure 7. Transfer Characteristic for Various Junction Temperatures

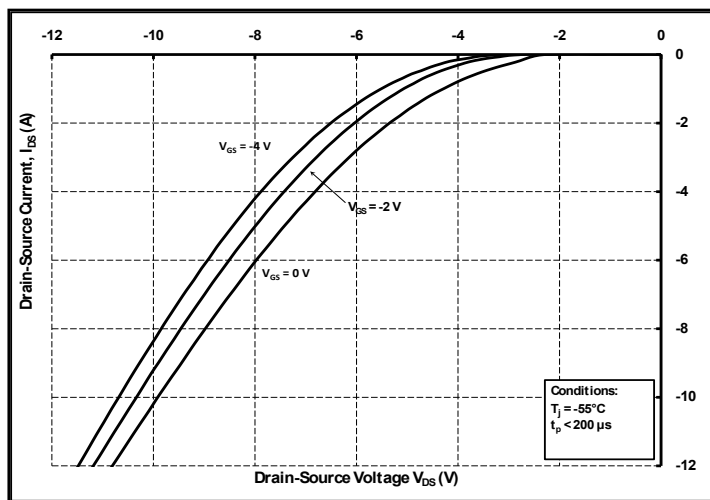
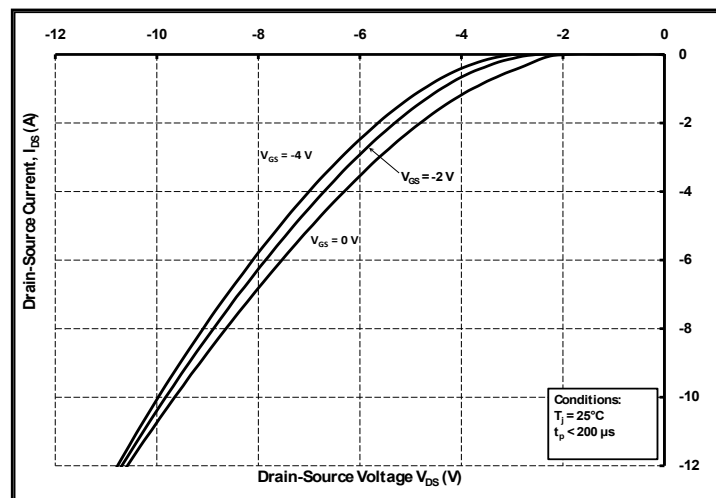
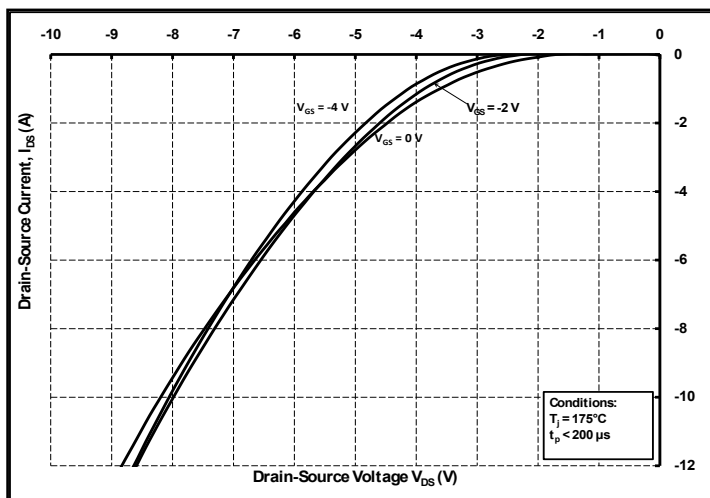
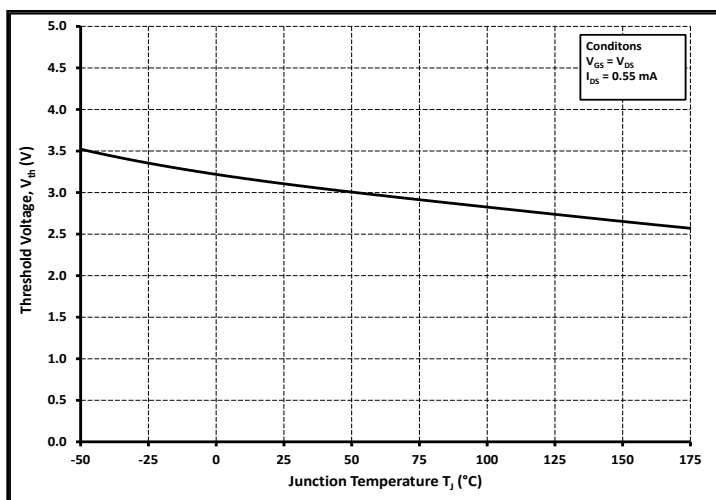
Figure 8. Body Diode Characteristic at -55°C Figure 9. Body Diode Characteristic at 25°C Figure 10. Body Diode Characteristic at 175°C 

Figure 11. Threshold Voltage vs. Temperature

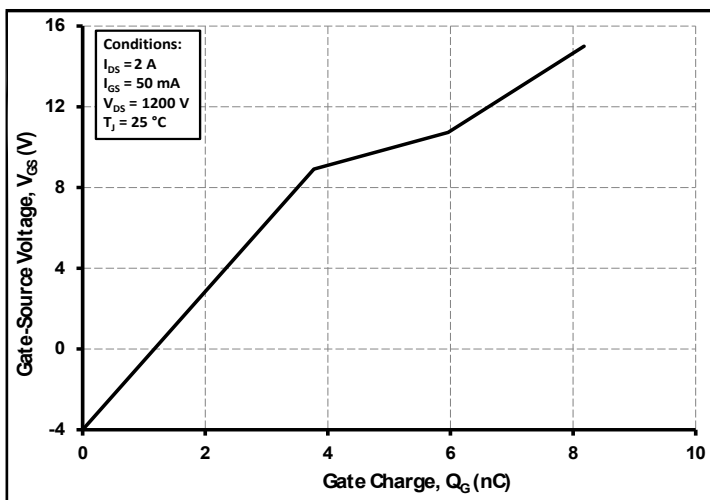


Figure 12. Gate Charge Characteristics

Typical Performance

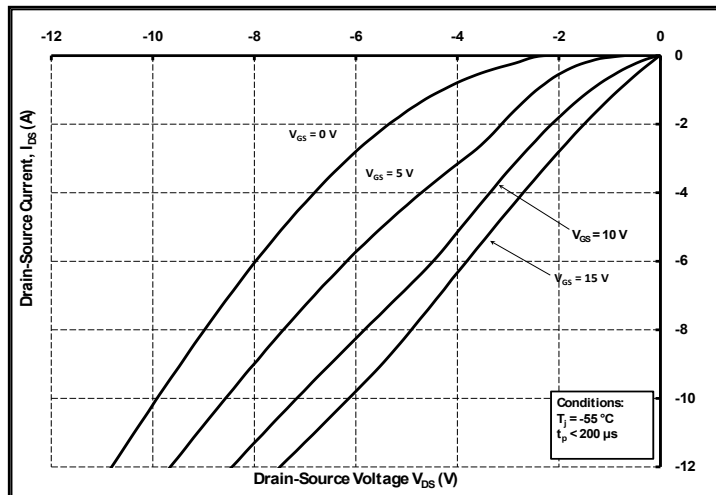


Figure 13. 3rd Quadrant Characteristic at -55 °C

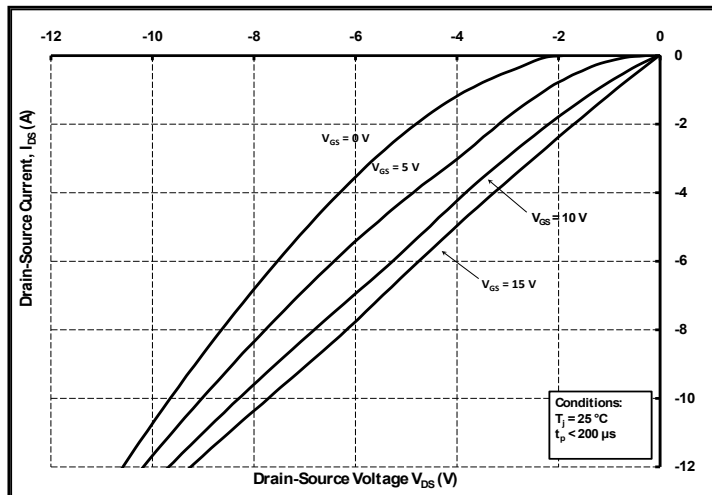


Figure 14. 3rd Quadrant Characteristic at 25 °C

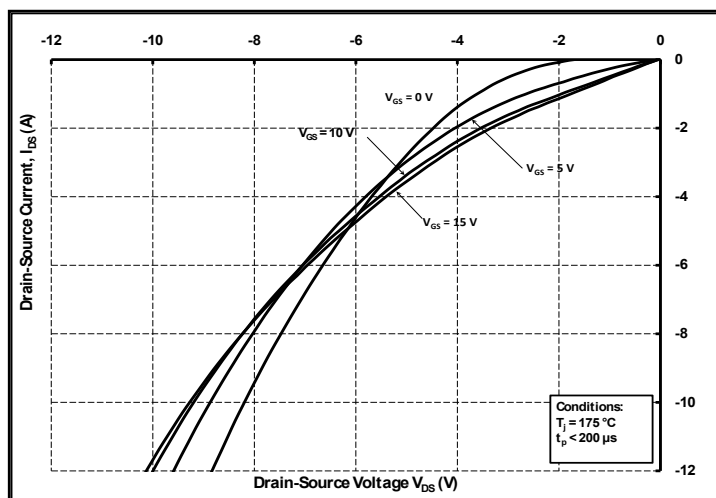


Figure 15. 3rd Quadrant Characteristic at 175 °C

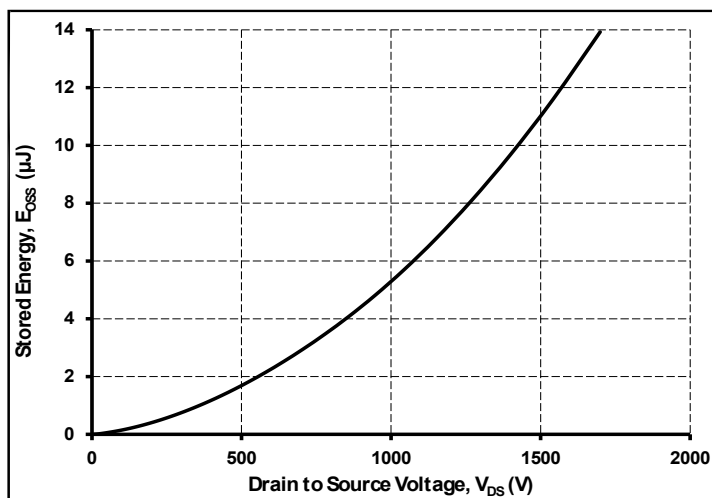


Figure 16. Output Capacitor Stored Energy

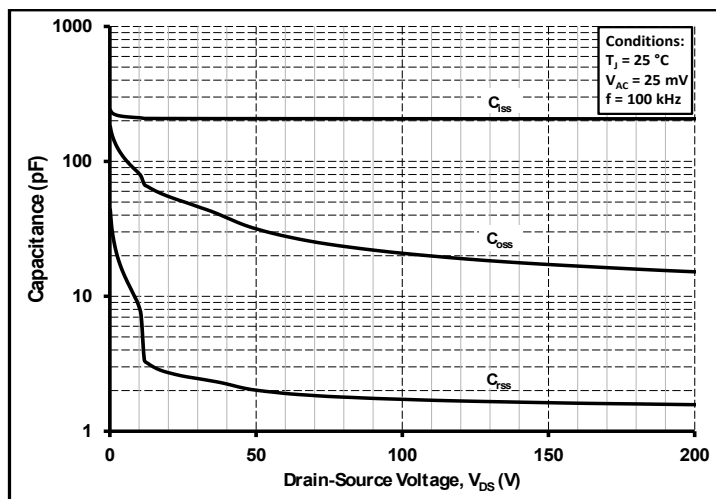


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

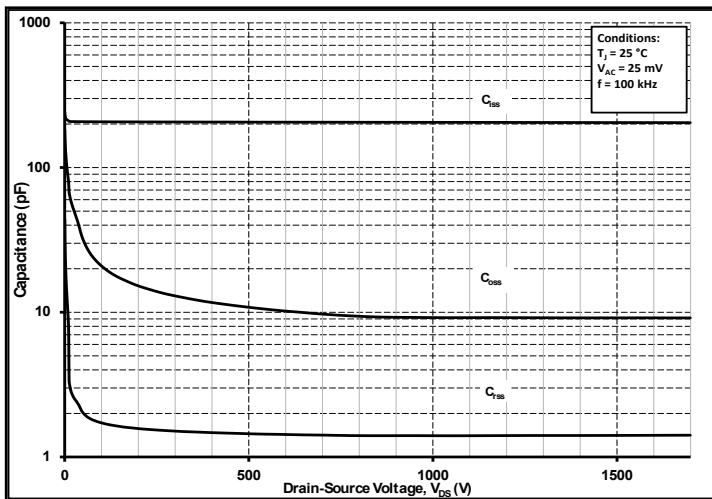


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1700V)

Typical Performance

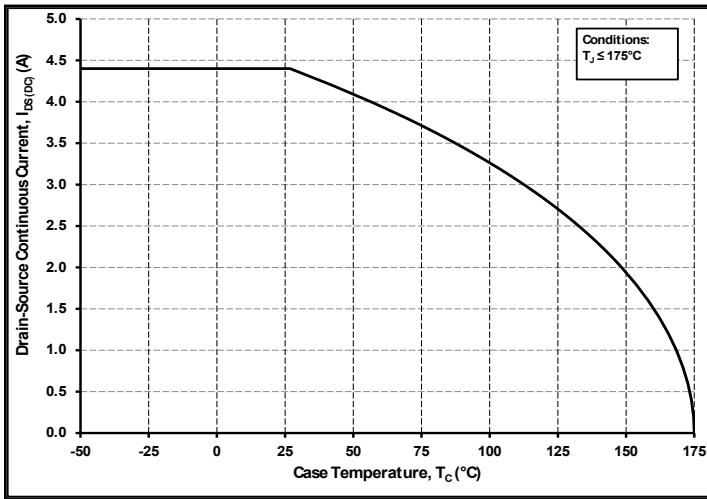


Figure 19. Continuous Drain Current Derating vs. Case Temperature

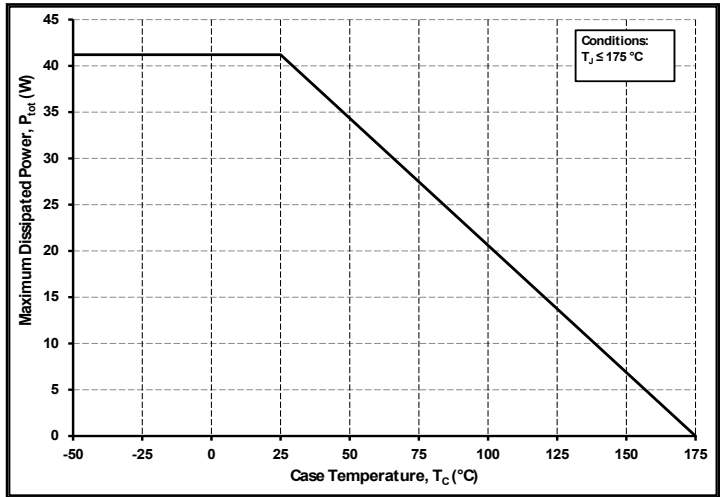


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

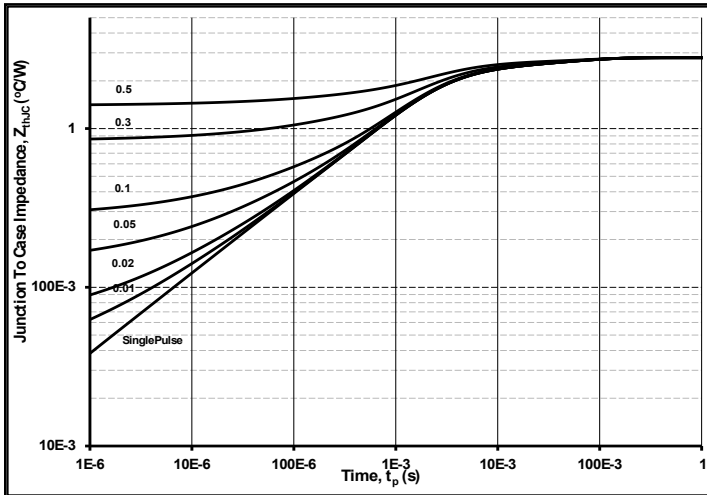


Figure 21. Transient Thermal Impedance (Junction - Case)

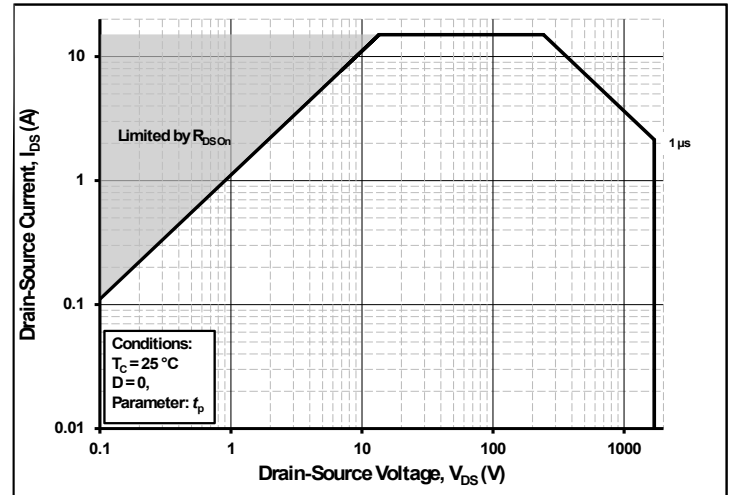
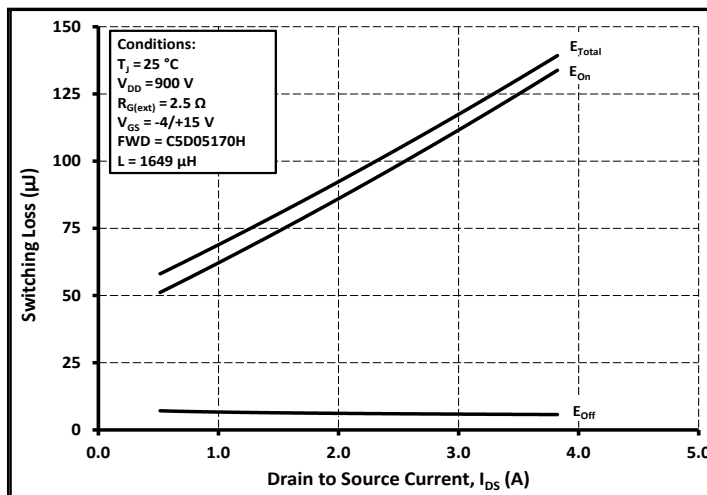
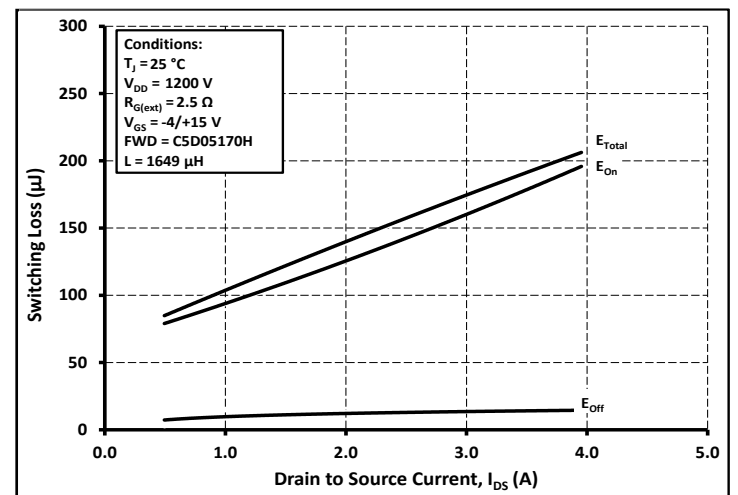


Figure 22. Safe Operating Area

Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 900V$)Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 1200V$)



Typical Performance

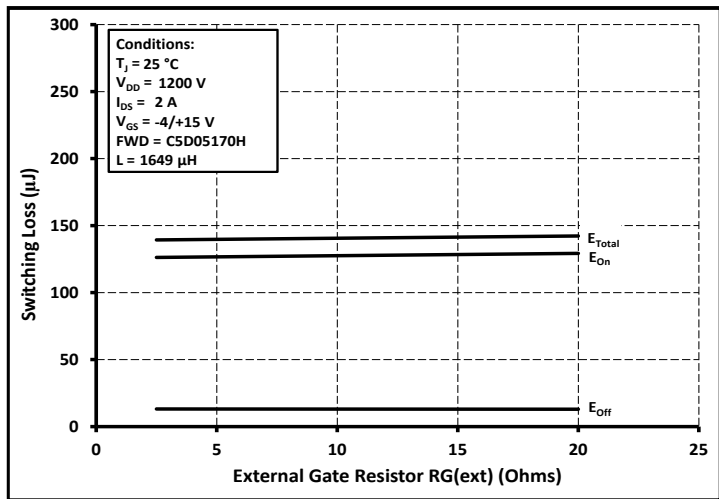


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

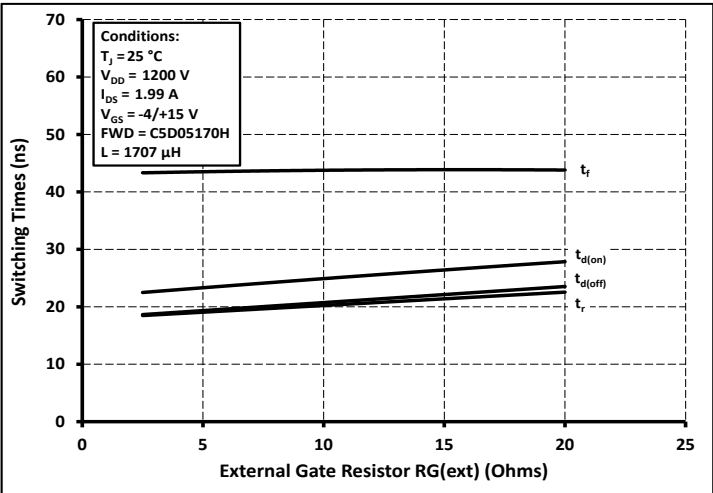


Figure 26. Switching Times vs. $R_{G(ext)}$

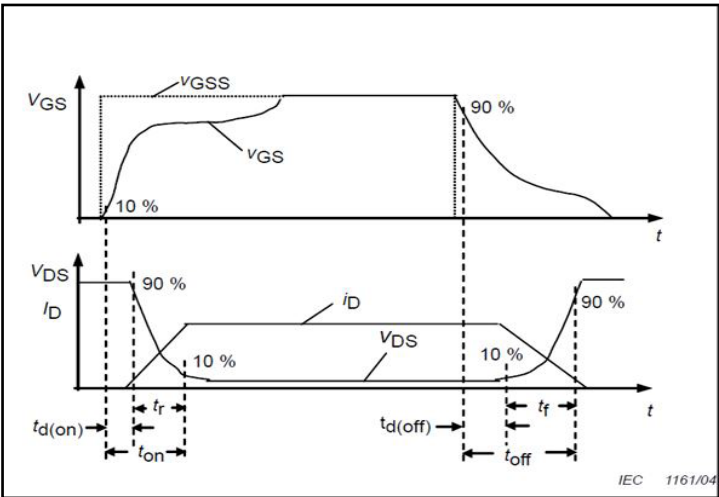


Figure 27. Switching Times Definition

Test Circuit Schematic

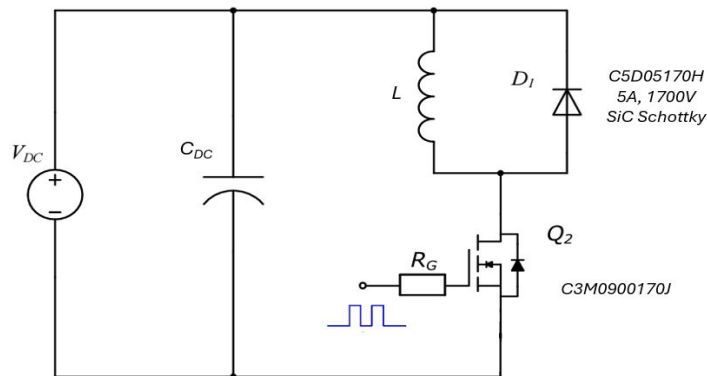
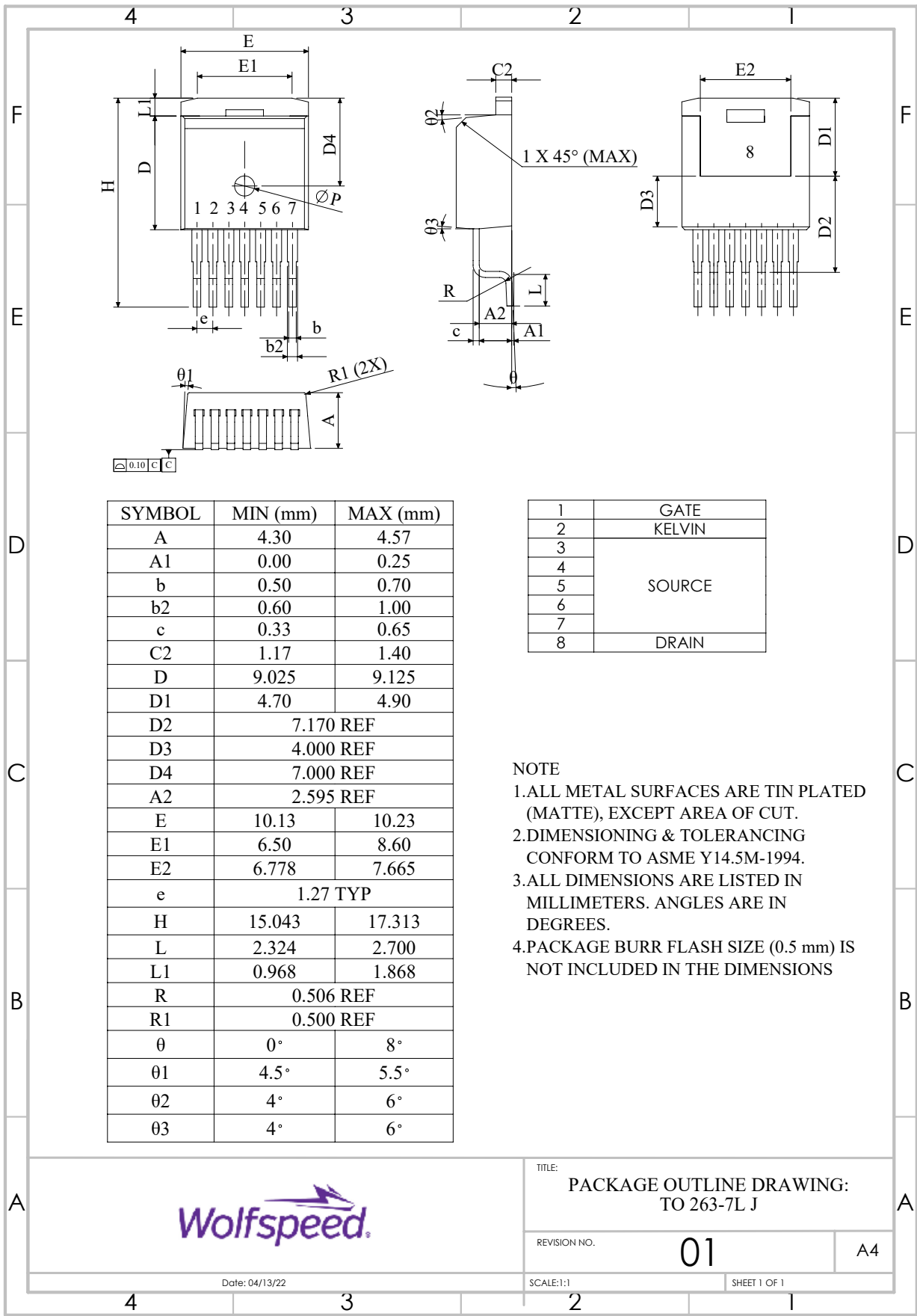


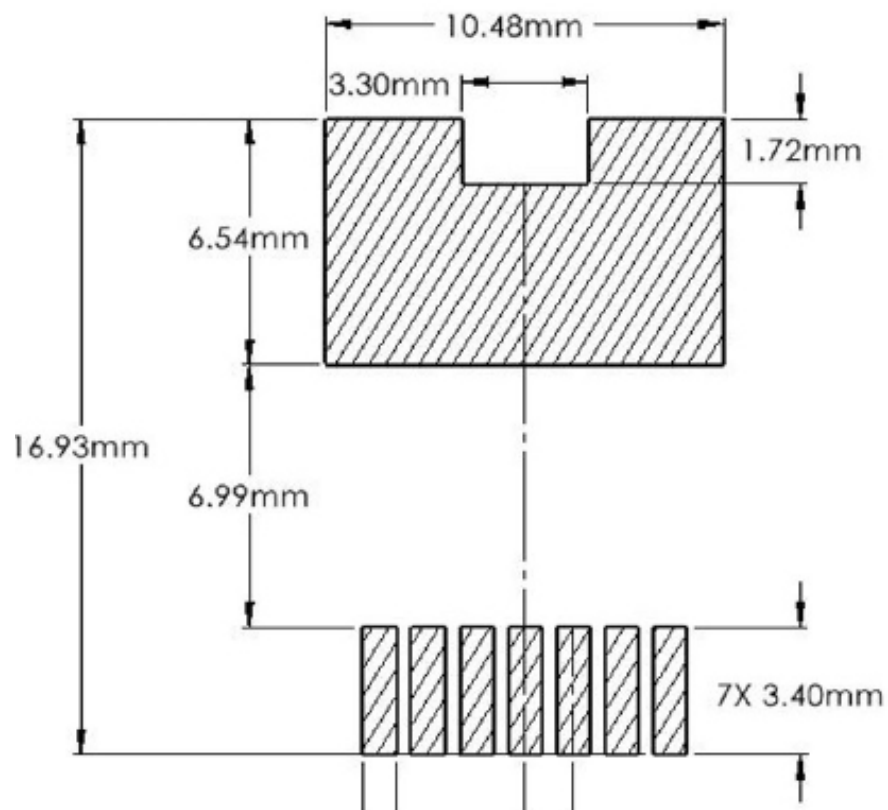
Figure 28. Clamped Inductive Switching
Waveform Test Circuit

Package Dimensions



Recommended Solder Pad Layout

All dimensions in mm





Revision history

Document Version	Date of release	Descriptiion of changes
1.0	December-2024	Initial datasheet
2.0	February-2025	Updated with latest characterization data

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